

Application Serial No. 10/803,264
Response to November 29, 2004 OA

MI22-2524

In the Claims

CLAIMS

Claims 1-30 (Canceled).

31. (Previously presented) An engagement probe comprising semiconductor bulk substrate material, the probe having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively removably engage a plurality of different single conductive pads on a plurality of different semiconductor substrates to test circuitry coupled with the single conductive pads.

32. (Currently amended) The engagement probe of claim 31 wherein the plurality of the projecting apexes comprises linear portions which are arranged in an interconnecting structure, ~~lacking lateral and~~ and wherein the plurality of the projecting apexes lack terminal ends.

33. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines.

34. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form at least one polygon.

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35. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes comprise outermost portions which constitute a first electrically conductive material, and wherein the respective different single conductive pads for which the probe is adapted have outermost portions constituting a second electrically conductive material; the first and second electrically conductive materials being different.

36. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes project from a common plane, the projecting apexes having respective tips and bases, the bases of adjacent projecting apexes being spaced from one another to define a penetration stop plane therebetween.

37. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes have a selected projecting distance, the projecting distance being about one-half the thickness of the respective different single conductive pads which the apparatus is adapted to engage.

38. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form the interconnecting structure comprising at least two polygons one of which is received entirely within the other.

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39. (New) The engagement probe of claim 31 wherein the semiconductor bulk substrate material comprises silicon.

40. (New) The engagement probe of claim 31 wherein the semiconductor bulk substrate material comprises monocrystalline silicon.

41. (New) The engagement probe of claim 31 wherein the semiconductor bulk substrate material comprises material of a semiconductor wafer.